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Vishay Siliconix

Automotive P-Channel 30 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY			
V _{DS} (V)	-30		
$R_{DS(on)}(\Omega)$ at $V_{GS} = -10 \text{ V}$	0.0044		
$R_{DS(on)}(\Omega)$ at $V_{GS} = -4.5 \text{ V}$	0.0071		
I _D (A)	-60		
Configuration	Single		
Package	PowerPAK SO-8L		

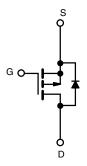
FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % Rq and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





ROHS COMPLIANT HALOGEN FREE



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-source voltage		V _{DS}	-30	V		
Gate-source voltage		V_{GS}	± 20	V		
Continuous drain current	T _C = 25 °C ^a		-60			
	T _C = 125 °C		-56			
Continuous source current (diode conduction) ^a		I _S	-60	Α		
Pulsed drain current ^b		I _{DM}	-155			
Single pulse avalanche current	L = 0.1 mH	I _{AS}	-41			
Single pulse avalanche energy	L = U.T IIII	E _{AS}	84	mJ		
Maximum power dissipation ^b	T _C = 25 °C	В	68	W		
	T _C = 125 °C	P _D	22			
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	°C		
Soldering recommendations (peak temperature) d, e			260	C		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-ambient	PCB mount ^c	R_{thJA}	68	°C/W		
Junction-to-case (drain)		R_{thJC}	2.2	C/VV		

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR4 material).
- d. See solder profile (www.vishay.com/doc?73257). For PowerPAK SO-8L, the end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static		<u> </u>						
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0, I _D = -250 μA		-30	-	-	V	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$		-2.0	-2.5		
Gate-source leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA	
Zero gate voltage drain current	I _{DSS}	V _{GS} = 0 V	V _{DS} = -30 V	-	-	-1		
		V _{GS} = 0 V	V _{DS} = -30 V, T _J = 125 °C	=	-	-50	μΑ	
		V _{GS} = 0 V	V _{DS} = -30 V, T _J = 175 °C	-	-	-200		
On-state drain current ^a	I _{D(on)}	V _{GS} = -10 V	$V_{DS} \ge -5 \text{ V}$	-30	-	-	Α	
5	(* /	V _{GS} = -10 V	I _D = -10 A	-	0.0036	0.0044	Ω	
	Б	V _{GS} = -10 V	I _D = -10 A, T _J = 125 °C	-	-	0.0060		
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = -10 V	I _D = -10 A, T _J = 175 °C	-	-	0.0068		
		V _{GS} = -4.5 V	I _D = -6 A	-	0.0059	0.0071		
Forward transconductance b	9 _{fs}	V _{DS} =	-15 V, I _D = -10 A	-	60	-	S	
Dynamic ^b					•		,	
Input capacitance	C _{iss}		V _{DS} = -25 V, f = 1 MHz	-	8200	10 700	pF	
Output capacitance	C _{oss}	$V_{GS} = 0 V$		-	950	1300		
Reverse transfer capacitance	C _{rss}	1		-	785	1050		
Total gate charge ^c	Qg		V _{DS} = -15 V, I _D = -5 A	-	169	260	nC	
Gate-source charge ^c	Q _{gs}	V _{GS} = -10 V		-	24	-		
Gate-drain charge ^c	Q _{gd}	1		-	32	-		
Gate resistance	R_g	f = 1 MHz		0.5	1.05	1.6	Ω	
Turn-on delay time ^c	t _{d(on)}		$V_{DD} = -15 \text{ V}, R_1 = 3 \Omega$		23	35	ns	
Rise time ^c	t _r	V _{DD} :			19	30		
Turn-off delay time ^c	t _{d(off)}	$I_D \cong -5 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		-	72	120		
Fall time ^c	t _f	1			14	25		
Source-Drain Diode Ratings and Charac	teristics ^b	-				l		
Pulsed current ^a	I _{SM}			-	-	-155	Α	
Forward voltage	V _{SD}	I _F = -10 A, V _{GS} = 0 V		-	-0.75	-1.2	V	
Body diode reverse recovery time	t _{rr}	I _F = 10 A, di/dt = 100 A/μs		-	39	90	ns	
Body diode reverse recovery charge	Q _{rr}			_	45	100	nC	
Reverse recovery fall time	t _a			-	22	-		
Reverse recovery rise time	t _b			_	19	-	ns	
	-10	1				1	l	

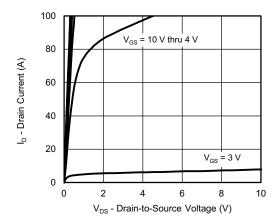
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

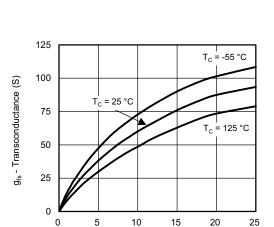
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

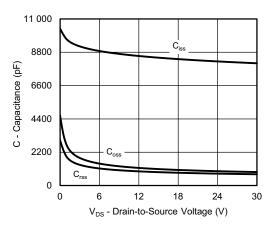


Output Characteristics

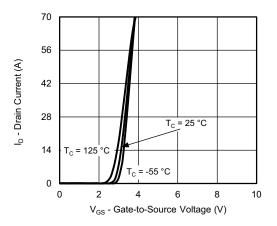


Transconductance

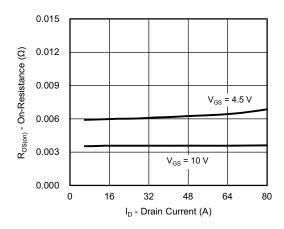
I_D - Drain Current (A)



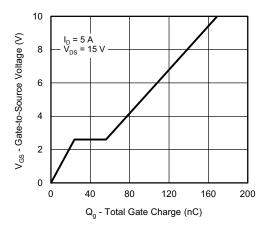
Capacitance



Transfer Characteristics



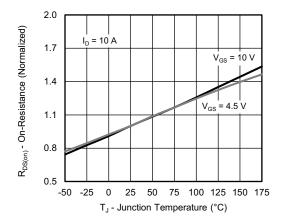
On-Resistance vs. Drain Current



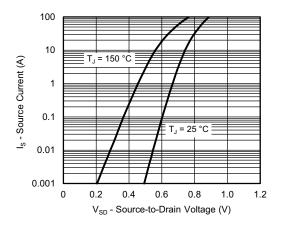
Gate Charge



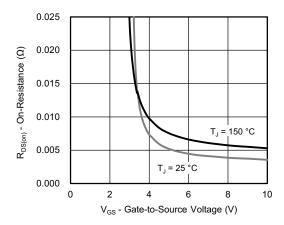
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



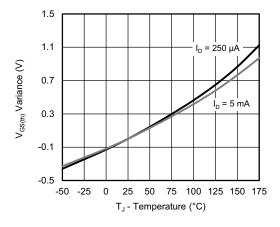
On-Resistance vs. Junction Temperature



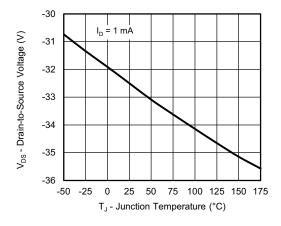
Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



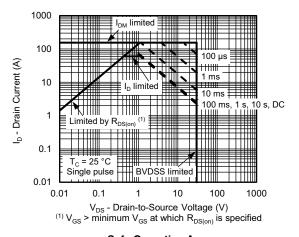
Threshold Voltage



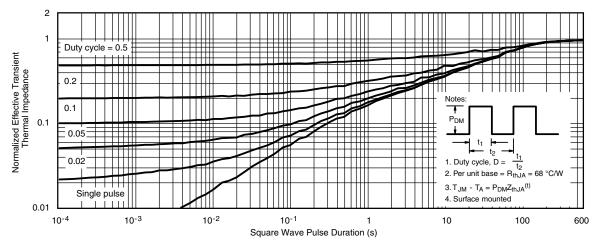
Drain-Source Breakdown vs. Junction Temperature



THERMAL RATINGS (T_C = 25 °C, unless otherwise noted)



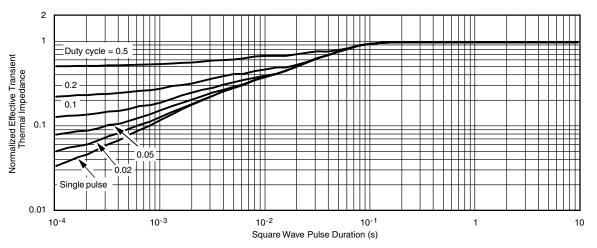
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient

THERMAL RATINGS (T_C = 25 °C, unless otherwise noted)

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Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?62806.



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